

**IN THE SPECIFICATION:**

Please replace paragraph 0032 with the following.

[0032] Figure 11 illustrates an embodiment of the present invention wherein circuit traces 24 are placed on the surface of a semiconductor substrate 26, more particularly, in a flip-chip ball grid array ("BGA") application. Like previous embodiments, the circuit traces 24 are configured such that a voltage reference trace 28 is placed between each of two signal traces 24 so that no signal trace 24 is placed immediately adjacent another signal trace 24. At least one of the solder balls 29 is operably coupled to at least one signal trace 24 and at least one solder ball 29 is operably coupled to a voltage reference trace 28.